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Date Date

Ayesha S. Wilks

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Trung T. Doan and Gurtej S. Sandhu Attorney Docket No.: 500300.02

Serial No. : 10/054,692 Group Art Unit : 3725

Filed: December 19, 2001 Examiner: William Hong

Title : POLISHING PAD REFURBISHER FOR IN SITU, REAL-TIME CONDITIONING

AND CLEANING OF A POLISHING PAD USED IN CHEMICAL-MECHANICAL

POLISHING OF MICROELECTRONIC SUBSTRATES

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AMENDMENT

TECHNOLOGY CENTER R3700

Sir:

Please amend the above-captioned patent application as follows:

In the Specification:

Please replace the paragraph beginning on column 2, line 18, with the following rewritten paragraph:

-CMP processes must also consistently and accurately produce a uniform, planar surface on the wafer because it is important to accurately focus the image of circuit patterns on the surface of the wafer. As the density of integrated circuits increases, it is often necessary to accurately focus the critical dimensions of the circuit pattern to better than a tolerance of approximately 0.1 μ m. Focusing the circuit patterns to such small tolerances, however, is very difficult when the distance between the emission source and the surface of the wafer varies

because the surface of the wafer is not uniformly planar. In fact, several devices may be defective on a wafer with a non-uniformly planar surface. Thus, CMP processes must create a highly uniform, planar surface.--